



# BAP64-06

Silicon PIN diode

Rev. 5.0 — 22 March 2019

Product data sheet

## 1 Product profile

### 1.1 General description

Two planar PIN diodes in common anode configuration in a SOT23 small SMD plastic package.

### 1.2 Features and benefits

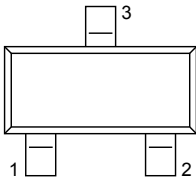
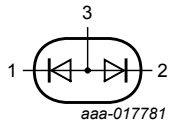
- High voltage, current controlled
- RF resistor for RF attenuators and switches
- Low diode capacitance
- Low diode forward resistance
- Low series inductance
- For applications up to 3 GHz
- AEC-Q101 qualified

### 1.3 Applications

- RF attenuators and switches

## 2 Pinning information

Table 1. Discrete pinning

Pin	Description	Simplified outline	Symbol
1	cathode 1	 top view	 aaa-017781
2	cathode 2		
3	common connection		



### 3 Ordering information

Table 2. Ordering information

Type number	Package		Version
	Name	Description	
BAP64-06	-	plastic surface-mounted package; 3 leads	SOT23

### 4 Marking

Table 3. Marking

Type number	Marking	Description
BAP64-06	6K*	* = t : made in Malaysia
		* = W : made in China

### 5 Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).  
Values are specified per diode.

Symbol	Parameter	Conditions	Min	Max	Unit
$V_R$	reverse voltage		-	175	V
$I_F$	forward current		-	100	mA
$P_{tot}$	total power dissipation	$T_{sp} = 90\text{ °C}$	-	250	mW
$T_{stg}$	storage temperature		-65	+150	°C
$T_j$	junction temperature		-65	+150	°C

### 6 Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Typ	Unit
$R_{th(j-sp)}$	thermal resistance from junction to solder point		220	K/W

### 7 Characteristics

Table 6. Characteristics

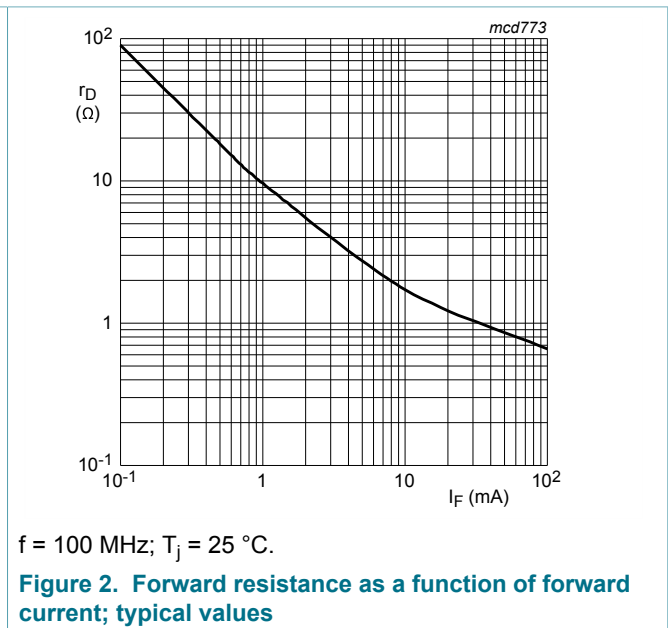
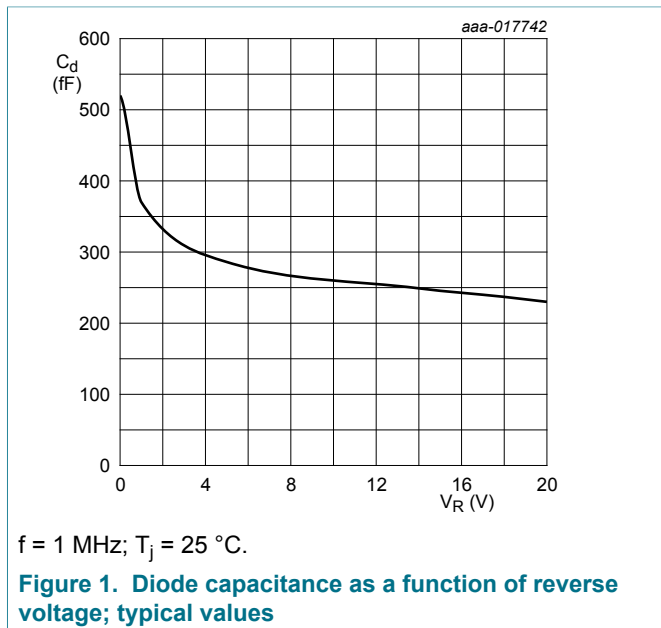
Values are specified per diode;  $T_j = 25\text{ °C}$  unless otherwise specified.

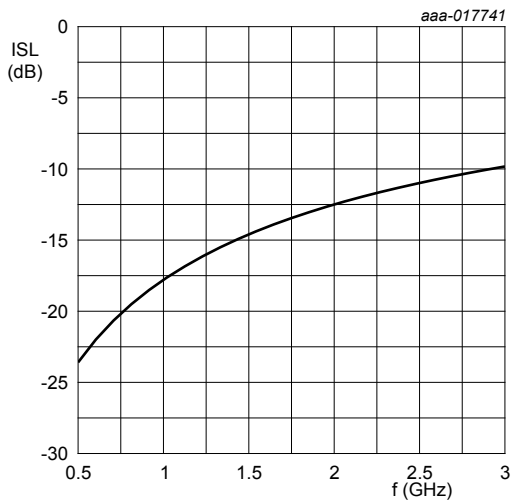
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_F$	forward voltage	$I_F = 50\text{ mA}$	-	0.95	1.1	V
$I_R$	reverse current	$V_R = 60\text{ V}$	-	-	10	$\mu\text{A}$
		$V_R = 20\text{ V}$	-	-	1	$\mu\text{A}$
$C_d$	diode capacitance	see <a href="#">Figure 1</a> ; $f = 1\text{ MHz}$ ;				
		$V_R = 0\text{ V}$	-	0.52	-	pF

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
		$V_R = 1\text{ V}$	-	0.37	-	pF
		$V_R = 20\text{ V}$	-	0.23	0.35	pF
$r_D$	diode forward resistance	see <a href="#">Figure 2</a> ; $f = 100\text{ MHz}$ ;	[1]			
		$I_F = 0.5\text{ mA}$	-	20	40	$\Omega$
		$I_F = 1\text{ mA}$	-	10	20	$\Omega$
		$I_F = 10\text{ mA}$	-	2.0	3.8	$\Omega$
		$I_F = 100\text{ mA}$	-	0.7	1.35	$\Omega$
$T_L$	charge carrier life time	when switched from $I_F = 10\text{ mA}$ to $I_R = 6\text{ mA}$ ; $R_L = 100\ \Omega$ ; measured at $I_R = 3\text{ mA}$	-	1.55	-	$\mu\text{s}$
$L_S$	series inductance		-	1.4	-	nH

[1] Guaranteed on AQL basis: inspection level S4, AQL 1.0.

### 7.1 Graphical data

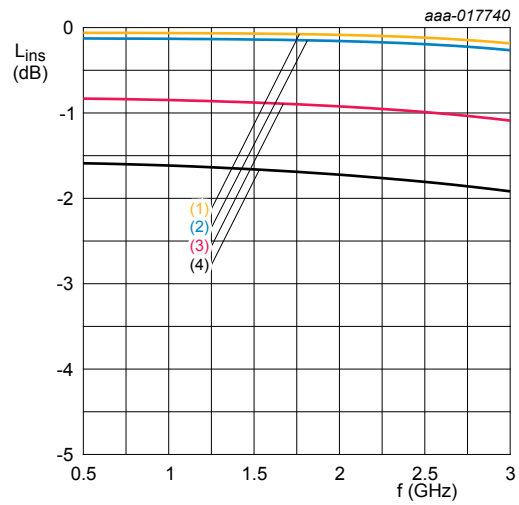




$T_{amb} = 25\text{ }^{\circ}\text{C}$

Diode zero biased and inserted in series with a 50  $\Omega$  stripline circuit

**Figure 3. Isolation of the diode as a function of frequency; typical values**



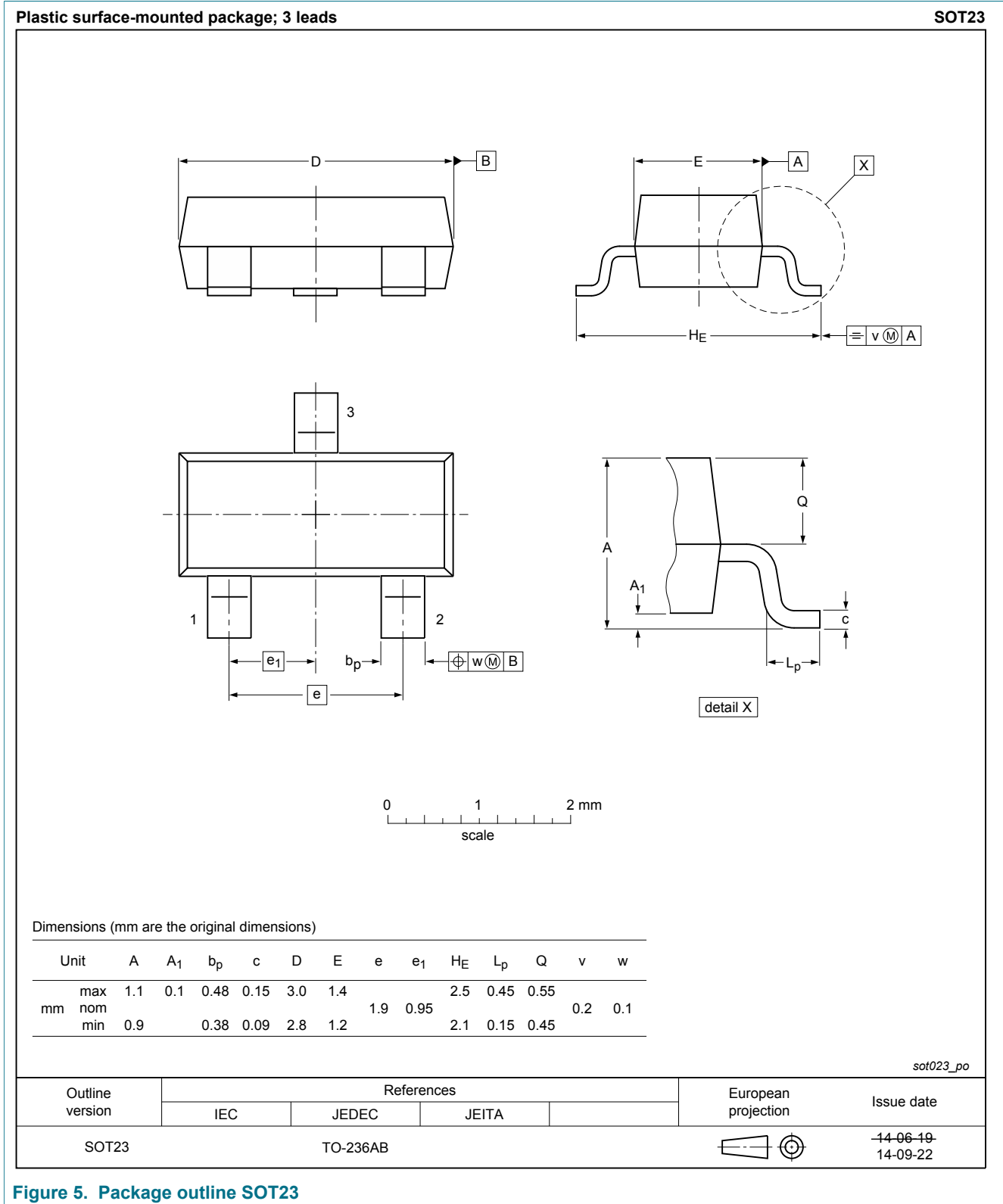
$T_{amb} = 25\text{ }^{\circ}\text{C}$

1.  $I_F = 100\text{ mA}$
2.  $I_F = 10\text{ mA}$
3.  $I_F = 1\text{ mA}$
4.  $I_F = 0.5\text{ mA}$

Diode inserted in series with a 50  $\Omega$  stripline circuit and biased via the analyzer Tee network

**Figure 4. Insertion loss of the diode as a function of frequency; typical values**

**8 Package outline**



**Figure 5. Package outline SOT23**

## 9 Abbreviations

Table 7. Abbreviations

Acronym	Description
AQL	acceptable quality level
PIN	P-type, intrinsic, N-type
SMD	surface mounted device
S4	special inspection level 4

## 10 Revision history

Table 8. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BAP64-06 v.5	20190311	Product data sheet	-	BAP64-06 v.4
Modifications:	<ul style="list-style-type: none"> <li>changed <math>V_R</math> condition of <math>I_R</math> from 175 V to 60 V</li> </ul>			
BAP64-06 v.4	20150428	Product data sheet	-	BAP64-06 v.3.1
Modifications:	<ul style="list-style-type: none"> <li>The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors.</li> <li>Legal texts have been adapted to the new company name where appropriate.</li> <li>AEC-Q101 qualified</li> </ul>			
BAP64-06_v.3 (9397 750 06664)	20010217	Product specification	-	BAP64-06 v.2
BAP64-06 v.2 (9397 750 06911)	20000322	Product specification	-	BAP64-06_N v.1
BAP64-06_N v.1 (9397 750 08033)	19991217	Preliminary specification	-	-

## 11 Legal information

### 11.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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